FIG. 1 MASTER SUBSTRATE S10 -PHOTORESIST COATING S12 -LASER BEAM RADIATION S14 -**DEVELOPMENT** MASTERING PROCESS FORMING ELECTRODE LAYER (NI SPUTTERING) S16 -**PLATING** S18 -STAMPER S20 ~ S22 -SUBSTRATE INJECTION-MOLDING S24 -RECORDING LAYER SPUTTERING DISC > MANUFACTURING **PROCESS** S26 **COVER LAYER** S28 -DISC

FIG. 2

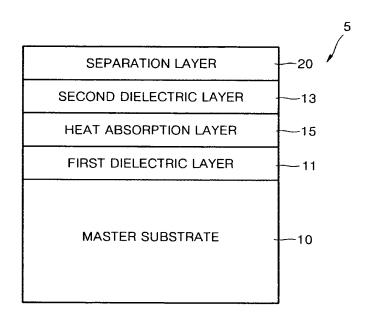


FIG. 3

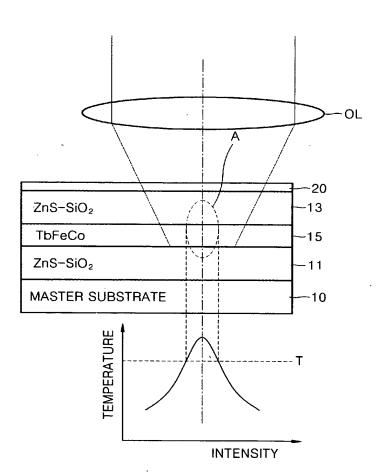


FIG. 4

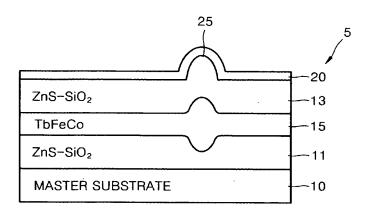


FIG. 5

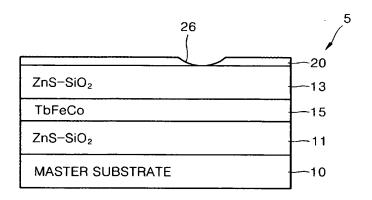
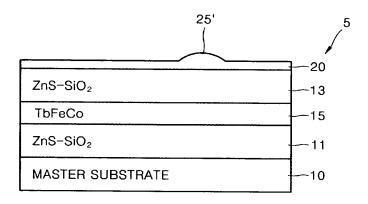


FIG. 6



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FIG. 7A

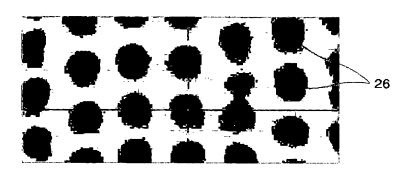


FIG. 7B

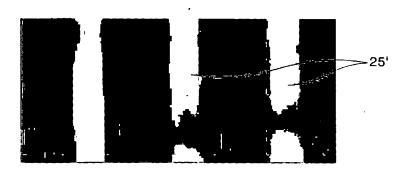


FIG. 8A

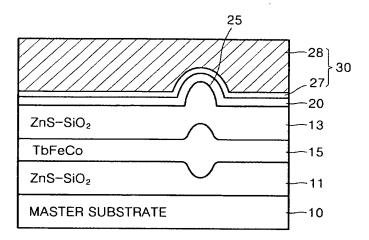


FIG. 8B

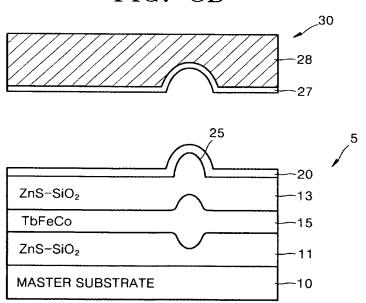


FIG. 9

